# **BGA Heat Sink - High Performance** maxiFLOW/superGRIP





ATS Part#: **ATS-X50250B-C1-R0** 

Description: 25.00 x 25.00 x 7.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP

Heat Sink Type: maxiFLOW
Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

\*Image above is for illustration purpose only.

#### **Features & Benefits**

- Designed for 25 x 25 mm components
- · Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

#### **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	8.6 °C/W	6.7 °C/W	5.8 °C/W	5.1 °C/W	4.7 °C/W	4.3 °C/W	4.1 °C/W
	Ducted Flow	6.1	N/A	N/A	N/A	N/A	N/A	N/A

### **Product Detail**

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	25.00 mm	25.00 mm	7.50 mm	36.4 mm	T766	BLUE-ANODIZED
*Image above is for illustration purpose only.	<ul> <li>Dimension</li> <li>Thermal papplication</li> <li>ATS reserperforman</li> <li>ATS certifities</li> </ul>	ves the right to upda	eight from the bottor e provided for referen ate or change its proc k assembly is RoHS	nce only. Actual perfucts without notice	ormance to improv	may vary by





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